

CHE323/CHE384
Chemical Processes for Micro- and Nanofabrication
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Lecture 64

Nanoimprint Lithography, part 2

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Nanoimprint Lithography

- Advantages of Imprint Lithography
 - Relatively inexpensive
 - Easy to get high resolution
 - Can be used for mass production
- Disadvantages of Imprint Lithography
 - Defects
 - Overlay
 - Throughput (for semiconductor lithography)
 - Template Manufacturing (1X)

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Problem - Defects

Fig. 9 Examples of commonly observed J-FIL defects (Ref. 11).
M. Malloy, L. Litt, S. Johnson, S. Resnick, and D. Lovell, "Jet and flash imprint defectivity – assessment and reduction for semiconductor applications," *Proc. SPIE* 7970, 797006 (2011).

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Problem – Magnification Correction (Overlay)

- When aligning new pattern to old, differences in thermal expansion can mean the new template is not the same size as the existing substrate (magnification error)
- Solution: squeeze or stretch the template

Magnification mechanics
Template
Substrate
Uniaxial loading: 0 psi, 20 psi, 50 psi
Biaxial loading: Active area 0 psi, 20 psi, 50 psi

© Chris Mack 4 Source: Molecular Imprints

Problem – Throughput

- It takes time to dispense the fluid and press the template
- Attempting to go too fast increases defectivity (fluid doesn't fill into the small openings of the template)
- But imprint heads are small and cheap – so use many of them
 - But templates are not cheap!

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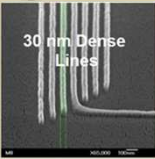
Problems - Status

Current Status of NIL		
Attribute	Target	Status
Template		
Master CDU	2.4nm	1.2nm
Image Placement	3nm	4nm
Master Defectivity	0.1/cm ²	10/cm ²
Replica Defectivity	1/cm ²	TBD
Imprint		
LER	2nm	2nm
Fill time	1 sec	2 sec
Overlay Accuracy	8nm	10nm
Defectivity	0.1/cm ²	10/cm ²

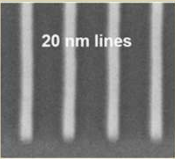
Fig. 14 Current status of jet and flash imprint lithography.
Higashi, et al., "Nanoimprint Lithography and Future Patterning for Semiconductor Manufacturing", *JM3* 10(4) p. 043008 (2011).

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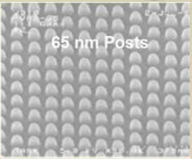
NIL Applications



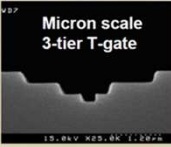
30 nm Dense Lines



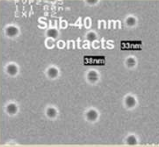
20 nm lines



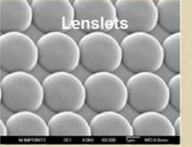
65 nm Posts



Micron scale
3-tier T-gate



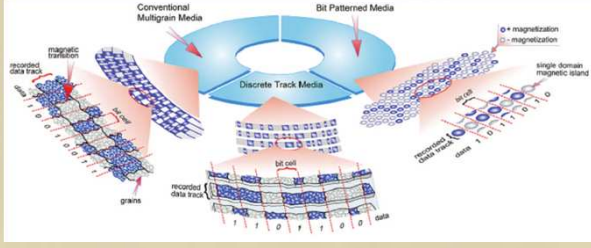
Sub-40 nm
Contacts



Lenslets

Source: Molecular Imprints © Chris Mack


NIL Applications



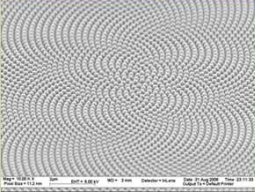
Bit patterned media (From Hitachi Global Storage)

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NIL Applications




Photonic Crystal Waveguide
(physicsworld.com, Apr 8, 2005)




LED Surface Pattern

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Commercial Systems



Obducat – thermal NIL, hot embossing, UV NIL, combined Thermal and UV




Nanonex – thermal NIL, hot embossing, UV NIL, alignment capability

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Commercial Systems



Imprio 300



NuTera HD7000

Molecular Imprints – UV step and flash NIL, geared towards hard drive, LED, and semiconductor manufacturing

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Lecture 64: What have we Learned?

- What are the main advantages of NIL?
- What are the main disadvantages of NIL?
- How many applications of NIL can you name?

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